

Surface Mount Schottky Power Rectifier

This device employs the Schottky Barrier principle in a large area metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity protection diodes, in surface mount applications where compact size and weight are critical to the system.

Features

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- Highly Stable Oxide Passivated Junction
- Excellent Ability to Withstand Reverse Avalanche Energy Transients
- Guard-Ring for Stress Protection
- This is a Pb-Free Device

Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 217 mg (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Notch in Plastic Body Indicates Cathode Lead
- ESD Ratings: Machine Model = C
Human Body Model = 3B

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|---------------------------------|--------------|------------------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V_{RRM} V_{RWM} V_R | 100 | V |
| Average Rectified Forward Current (At Rated V_R , $T_L = 100^\circ\text{C}$) | $I_{F(AV)}$ | 3.0 | A |
| Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz) | I_{FSM} | 130 | A |
| Operating Junction Temperature Range (Note 1) | T_J | - 65 to +175 | $^\circ\text{C}$ |

THERMAL CHARACTERISTICS

| | | | |
|--------------------------------------|-----------------|----|--------------------|
| Thermal Resistance, Junction-to-Lead | $R_{\theta JL}$ | 11 | $^\circ\text{C/W}$ |
|--------------------------------------|-----------------|----|--------------------|

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.



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**SCHOTTKY BARRIER
RECTIFIERS
3.0 AMPERES, 100 VOLTS**



SMC
CASE 403

MARKING DIAGRAM



B310 = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
■ = Pb-Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

| Device | Package | Shipping† |
|-------------|------------------|------------------|
| MBRS3100T3G | SMC (Pb-Free) | 2500/Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MBRS3100T3G

ELECTRICAL CHARACTERISTICS

| Rating | Symbol | Value | Unit |
|--|--------|------------------------------|------|
| Maximum Instantaneous Forward Voltage (Note 2) ($i_F = 3.0\text{ A}$, $T_J = 25^\circ\text{C}$) ($i_F = 6.0\text{ A}$, $T_J = 25^\circ\text{C}$) ($i_F = 3.0\text{ A}$, $T_J = 125^\circ\text{C}$) ($i_F = 6.0\text{ A}$, $T_J = 125^\circ\text{C}$) | V_F | 0.79 0.90 0.62 0.70 | V |
| Maximum Instantaneous Reverse Current (Note 2) (Rated dc Voltage, $T_J = 25^\circ\text{C}$) (Rated dc Voltage, $T_J = 125^\circ\text{C}$) | i_R | 0.05 5.0 | mA |

2. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.

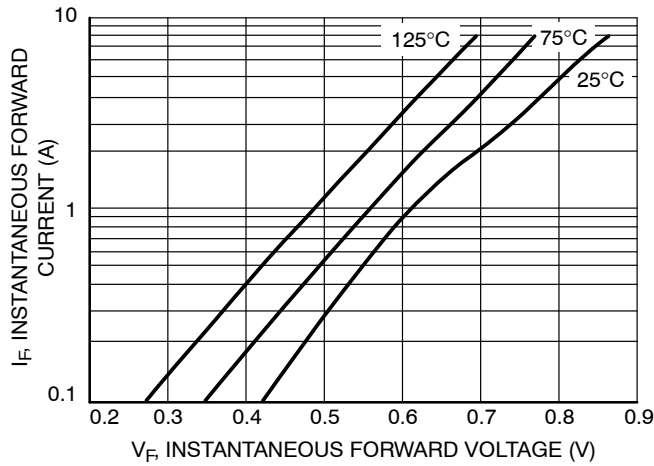


Figure 1. Typical Forward Voltage

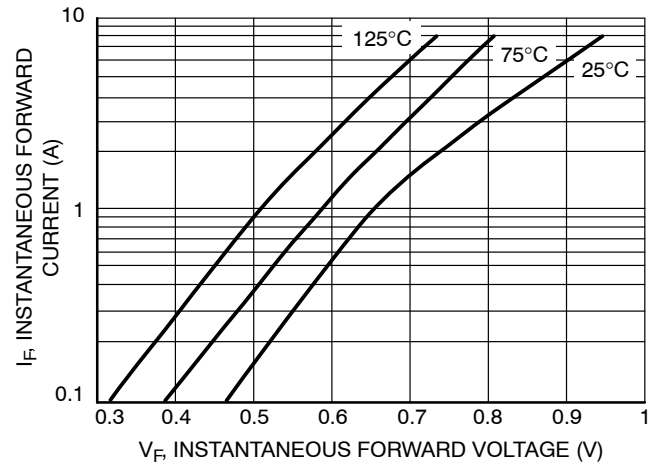


Figure 2. Maximum Forward Voltage

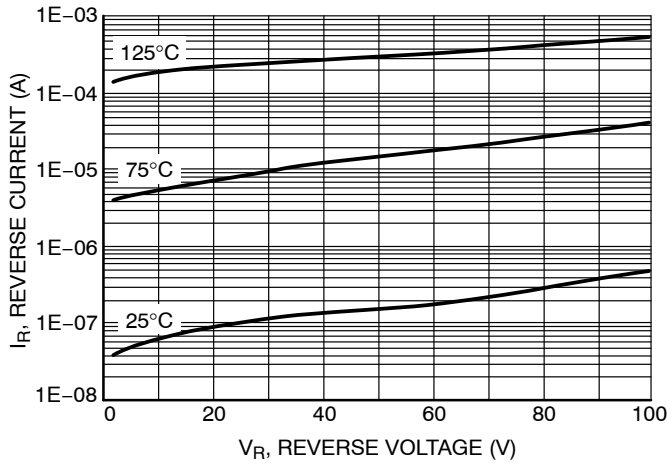


Figure 3. Typical Reverse Current

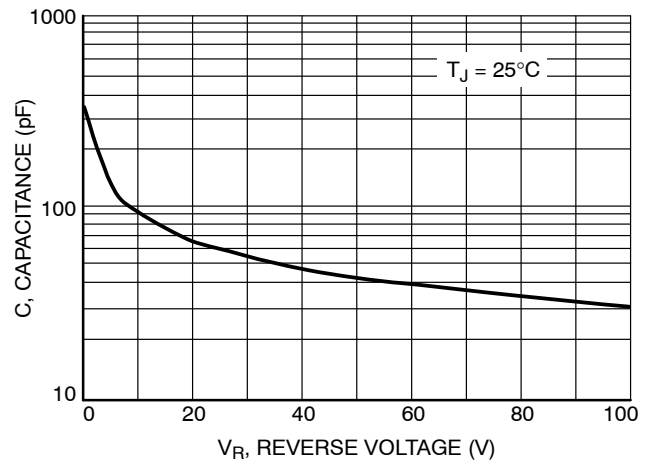


Figure 4. Typical Capacitance

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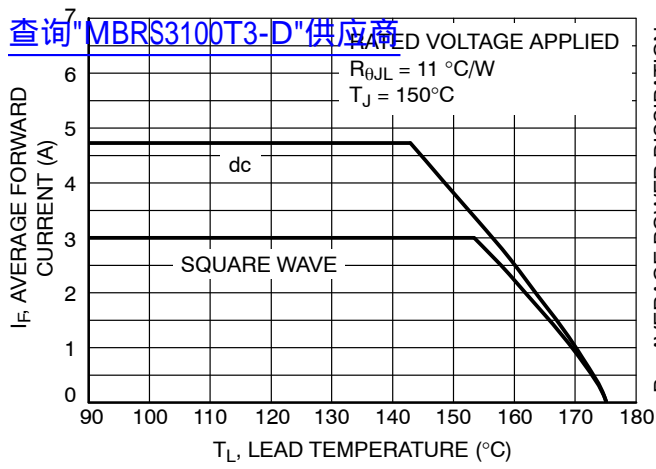


Figure 5. Current Derating – Lead

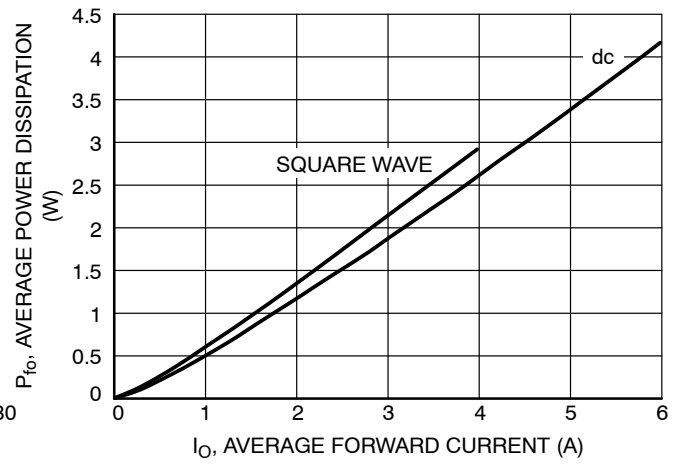


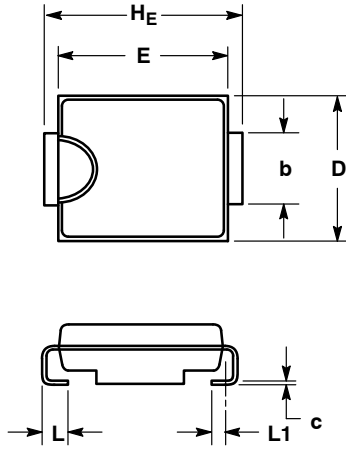
Figure 6. Forward Power Dissipation

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[查询"MBRS3100T3-D"供应商](#)

PACKAGE DIMENSIONS

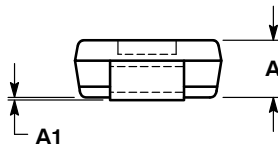
SMC
CASE 403-03
ISSUE E



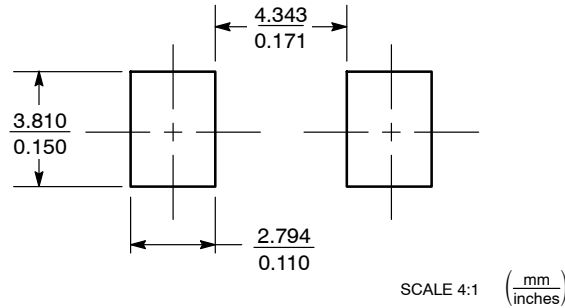
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.
4. 403-01 THRU -02 OBSOLETE, NEW STANDARD 403-03.


| DIM | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|------|-----------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 1.90 | 2.13 | 2.41 | 0.075 | 0.084 | 0.095 |
| A1 | 0.05 | 0.10 | 0.15 | 0.002 | 0.004 | 0.006 |
| b | 2.92 | 3.00 | 3.07 | 0.115 | 0.118 | 0.121 |
| c | 0.15 | 0.23 | 0.30 | 0.006 | 0.009 | 0.012 |
| D | 5.59 | 5.84 | 6.10 | 0.220 | 0.230 | 0.240 |
| E | 6.60 | 6.86 | 7.11 | 0.260 | 0.270 | 0.280 |
| HE | 7.75 | 7.94 | 8.13 | 0.305 | 0.313 | 0.320 |
| L | 0.76 | 1.02 | 1.27 | 0.030 | 0.040 | 0.050 |
| L1 | 0.51 REF | | | 0.020 REF | | |



SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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